Solderless Breadboard with Wire Kit





Kit Contents

Solderless Breadboard, 1660 Tie-Points, 6 Strips, 3 Binding Posts and 4 Rubber Foots, Jumper Wire kit.

- Breadboard Size: 166mm×108mm×8.5mm
- · Terminal Strips, Tie-point 1260
- Distribution Strips, Tie-point 400
- Binding Posts × 3 PCs (Red, Yellow and Black)
- Plate Size: 213mm×130mm×1.2mm
- Rubber Foots × 4 Pcs, Black

Part Number Table

Description	Part Number
Prototyping Kit, Solderless Breadboard, 1660 Tie-Points	21-19082

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